

1    **ABSTRACT OF THE DISCLOSURE**

2           A packaging method for preparing thin integrated circuits comprises:  
3   forming a circuit layer with multiple sections on a substrate; attaching  
4   multiple electronic elements to the circuit layer between two sections of the  
5   circuit layer; applying an encapsulant layer to protect the electronic elements;  
6   and removing the substrate to expose the circuit layer. By removing the  
7   substrate, the exposed circuit can be connected to another circuit board and  
8   the integrated circuit is much thinner.